


REVISIONS				
REV	DESCRIPTION	ECN	BY	DATE
A	RELEASED	J30135	K.S	6/13/93
B	REVISED	J40005	K.S	2/7/94
C	REVISED	J30072	N.H	6/13/95
D	REVISED	N06-0020	M.Z	01/11/06

90930-XXXXX

- PUSH ROD COLOR A: BLACK
- PUSH ROD LENGTH (DIM"L") A: 8mm
B: 13mm
- HDR SOLDER TAIL & EARTH PLATE A: R/A WITH E/P
F: R/A(SECOND DECK) WITH E/P
O: R/A WITHOUT E/P
- STAND-OFF HEIGHT (DIM"H") O: 0mm (none)
1: 4mm
2: 5mm
- MOUNT STYLE TO PCB & PUSH ROD POSITION O: TOP MOUNT & RIGHT PUSH ROD
1: TOP MOUNT & LEFT PUSH ROD
6: BOTTOM MOUNT & LEFT PUSH ROD

NOTE:
90930-111 MEANS EXACTLY SPECIAL VARIATION
SEE SHEET NO.6 REGARDING THIS FEATURE.

SHEET INDEX	ISSUE	D	B	B	B	B	D	B												
	SH NO.	1	2	3	4	5	6	7												
TOLERANCES UNLESS OTHERWISE SPECIFIED		MAT		DRAWN BY Hasegawa, M. / ENGR N. Hiyama / DATE 6/8/95										CUSTOMER COPY		TITLE 68P EJECTOR HEADER ASSY FOR TYPE I/II				
LINEAR		SEE NOTE ④																		
		FINISH		CRK																
ANGLES		SEE NOTE ⑤		APPD										THIRD ANGLE PROJ		SCALE 2/1	SIZE C	DWG. NO. 90930	REV D	SHEET 106

NOTE

1. EJECT FORCE 3.5Kg MAX.

2. ASSY PROCESS

2.1 TO MOUNT PART (A) ON PWB WITH 2 SCREWS (S1,S2) AND SOLDER.

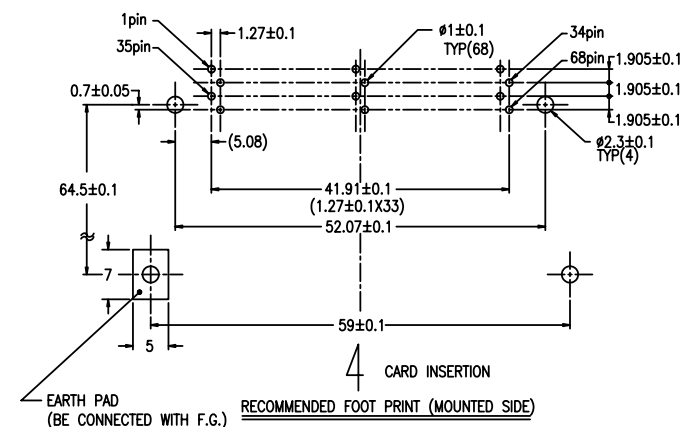
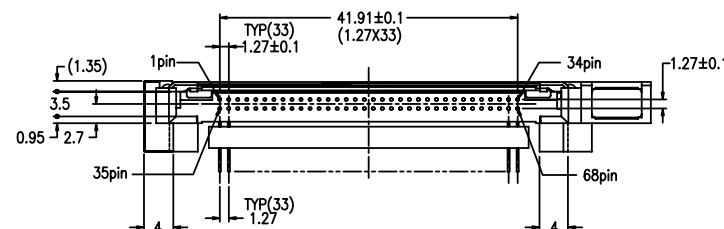
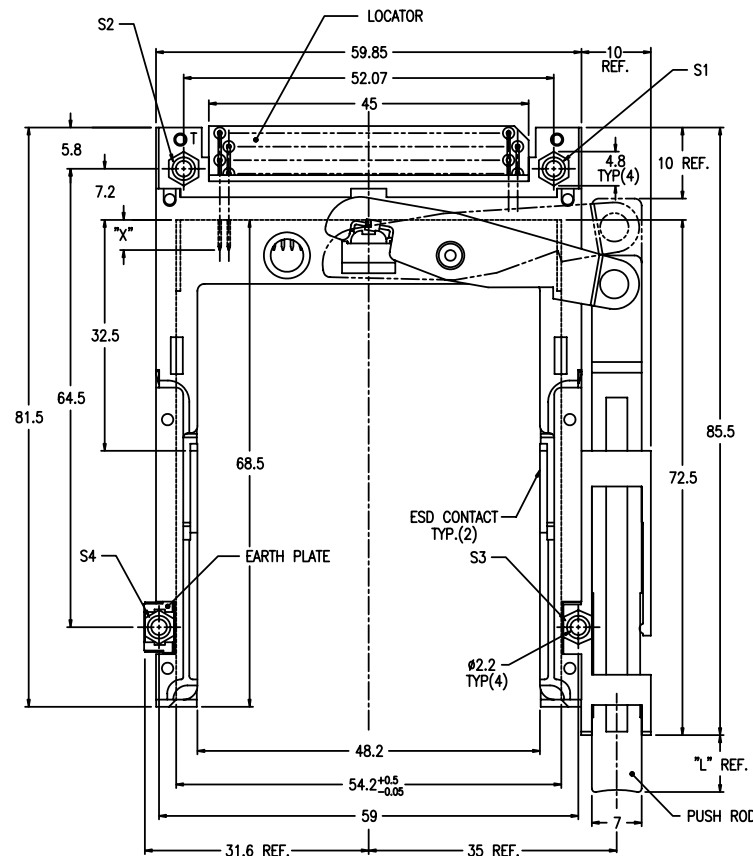
2.2 TO JOINT PART (B) TO PART (A), THEN FIX PART (B) WITH 2 SCREWS (S3,S4).

3. PUSH ROD TRAVEL 8.0mm REF.

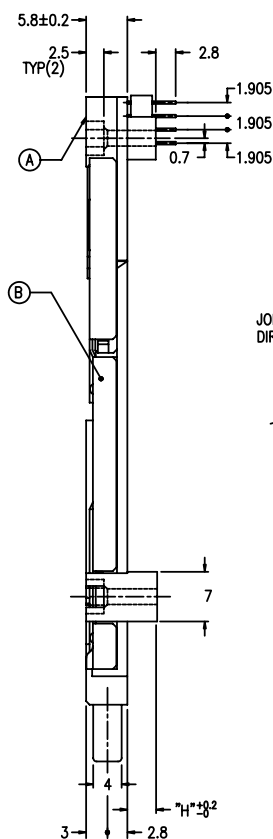
A	RELEASED
B	RELEASED

6. DIM "X"

7. SEE SHEET 1 REGARDING COMPONENTS.
8. GENERAL TOLERANCE : ± 0.3
9. IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

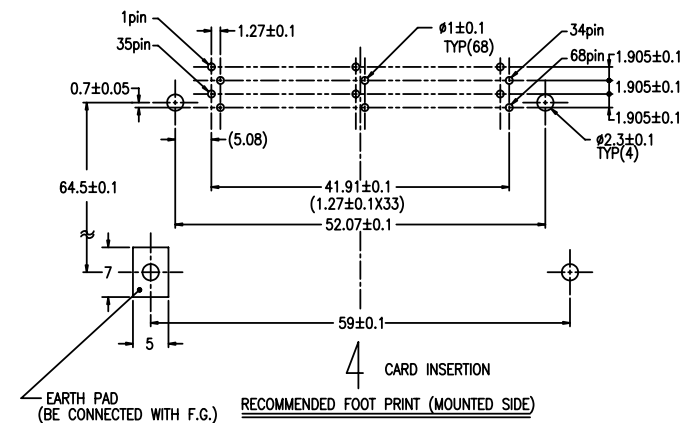


DF-003A REV C



DIM "X"	5.0±0.1	3.5±0.1	4.25±0.1
PIN NO.	1,17,34 35 51 68	36.67	OTHERS

11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

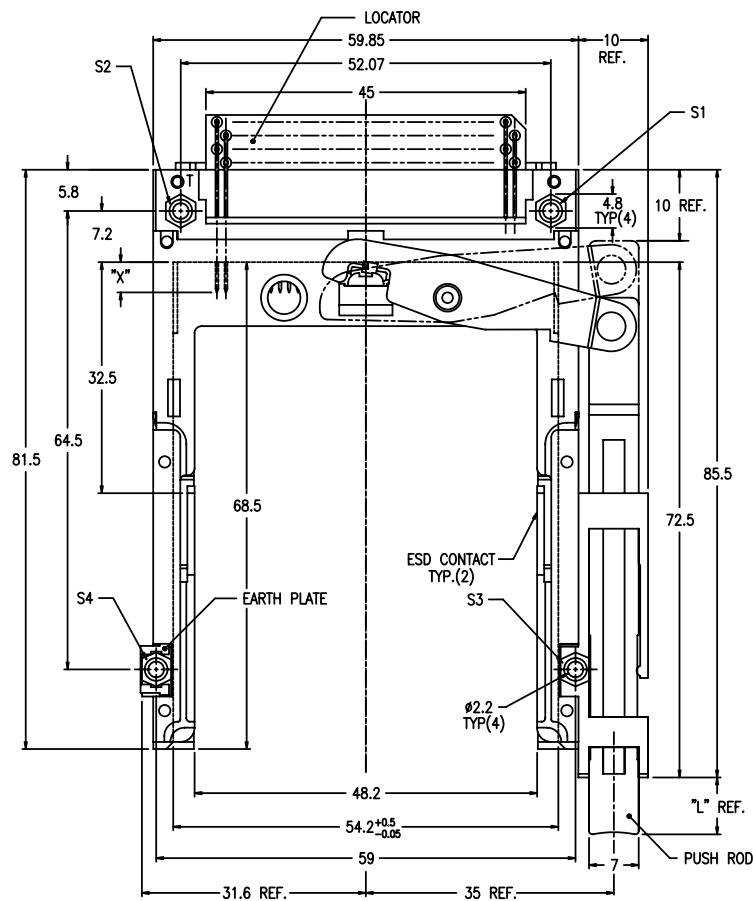
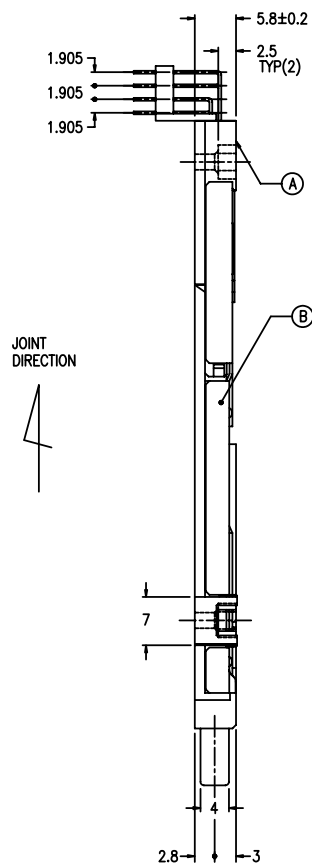
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68P EJECTOR HEADER ASSY FOR TYPE I/II
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SCALE	SIZE	DWG. NO.	REV	SHEET
2/1	C	90930	B	3 OF

PRODUCT NO.
90930-00FAA/00FAALF

REVISIONS				
REV	DESCRIPTION	ECN	BY	DATE
A	RELEASED	J30072	N.H	6/13/95
B	RELEASED	n06-0011	MZ	01/19/06



NOTE

- EJECT FORCE 3.5Kg MAX.
- ASSY PROCESS
 - TO MOUNT PART (A) ON PWB WITH 2 SCREWS (S1,S2) AND SOLDER.
 - TO JOINT PART (B) TO PART (A), THEN FIX PART (B) WITH 2 SCREWS (S3,S4).
- PUSH ROD TRAVEL 8.0mm REF.

④ MATERIAL

4.1 PART (A) (HEADER ASSY)
 HOUSING : LIQUID CRYSTAL POLYMER (LCP) UL94V-0
 PIN : COPPER ALLOY
 LOCATOR : 66NYLON UL94V-0 BLACK

4.2 PART (B) (EJECT MECHANISM ASSY)
 GUIDE : POLYPHENYLENE SULFIDE (PPS) UL94V-0 BLACK
 PUSH ROD : POLYPHTHARAMID UL94V-0 BLACK
 PLATES : STAINLESS STEEL
 EARTH PLATE : STAINLESS STEEL

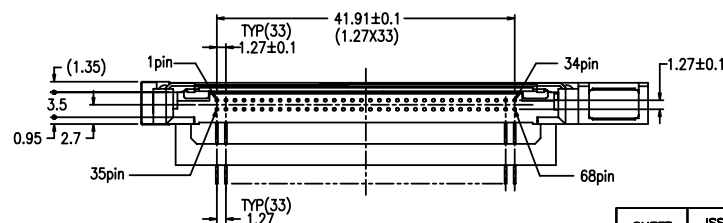
⑤ FINISH (PIN)

UNDER PLATING : 0.5 mm MIN. Ni
 CONTACT AREA : 0.1 mm MIN. GOLD OVER 0.5 mm MIN. Pd-Ni
 SOLDER TAIL : 2.5 mm MIN. Sn-Pb

6. DIM "X"

DIM "X"	5.0±0.1	3.5±0.1	4.25±0.1
PIN NO.	1,7,34 35,37,38	36,67	OTHERS

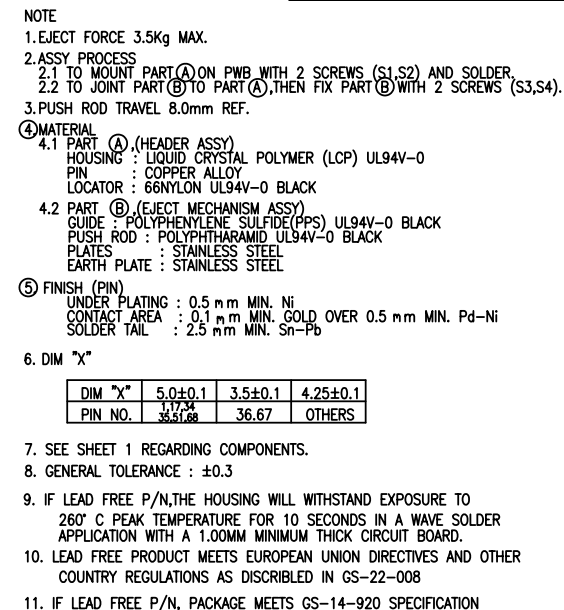
- SEE SHEET 1 REGARDING COMPONENTS.
- GENERAL TOLERANCE : ±0.3
- SEE 90953 FOR PCB LAYOUT.
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCIBLED IN GS-22-008
- IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
- IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.



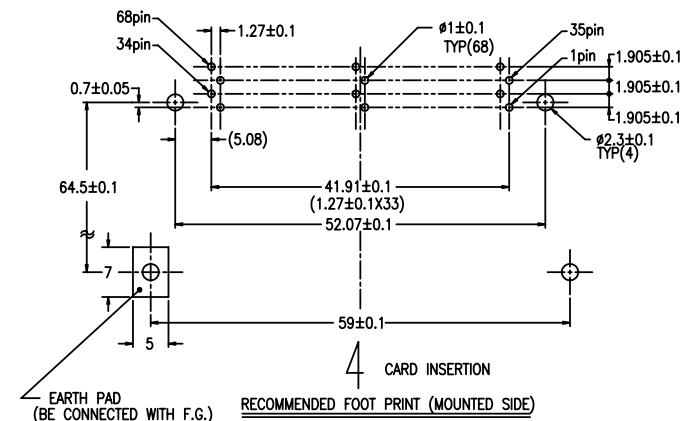
DF-003A REV C

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SHEET INDEX	ISSUE										TITLE
	SH NO.										
TOLERANCES UNLESS OTHERWISE SPECIFIED											68P EJECTOR HEADER ASSY FOR TYPE I/II
LINEAR											
ANGLES											SCALE 2/1 SIZE C DWG. NO. 90930 REV B SHEET 4 of 4
											CUSTOMER COPY
											THIRD ANGLE PROJ
											UNIT MM
											DRAWN BY
											CHECKED BY
											APPROVED BY
											DATE
											MATERIAL
											REVISION
											BY
											DATE



DIM "X"	5.0±0.1	3.5±0.1	4.25±0.
PIN NO.	1.17, 34 35 51 68	36.67	OTHERS

[illegible]

Technical drawing of a door latch assembly, showing side and cross-sectional views with dimensions and labels.

Top View (Side View):

- Overall width: 5.8 ± 0.2
- Header assembly (④) width: 2.5
- Joint direction (SEE NOTE ②) indicated by an arrow.
- Dimensions: 3.7, 2.8, $\phi 2.5$, 1.4 ± 0.1
- Push 1mm (SEE NOTE ②) indicated by an arrow.
- Vertical dimensions: 10 REF., 85.5, 72.5
- Eject mech. Assy (⑤) indicated by a line.
- Latch pin (⑥) indicated by a line.
- Push rod indicated by a line.
- Vertical dimension: $L = 10$ REF.

Bottom View (Cross-section A-A):

- Overall width: 1.1
- Header assembly (④) width: 2.5
- Joint direction (SEE NOTE ②) indicated by an arrow.
- Dimensions: 1.0, 1.0, 7.5 ± 0.15 , 5.2 ± 0.15 , 4 ± 0.2
- Vertical dimension: (5.8)
- Overall width: 0 ± 0.15 (SEE NOTE ⑦)

Labels and Notes:

- ④ HEADER ASSY
- ⑤ EJECT MECH. ASSY
- ⑥ LATCH PIN
- PUSH 1mm (SEE NOTE ②)
- JOINT DIRECTION (SEE NOTE ②)
- AFTER INSTALLATION OF LATCH PIN
- PUSH ROD
- 10 REF.
- $L = 10$ REF.
- $H = 4 \pm 0.2$
- 0 ± 0.15 (SEE NOTE ⑦)

SECTION "A-A" (4/1)

DF-003A REV. C

DO NOT SCALE PRINT THIS INFORMATION IS CONFIDENTIAL AND IS DISCLOSED TO YOU ON CONDITION THAT NO FURTHER DISCLOSURE IS

5.0±0.1	3.5±0.1	4.25±0.1
1.17±0.1		
35.61±0.05 pin	36.67 pin	OTHERS

⑦ SOLDER TAILS ARE TO BE WITHIN 0.15 ABOVE 0.15 BELOW HOUSING SURFACE.
 8. GENERAL TOLERANCE : ±0.3
 9. IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
 10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-22-008
 11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

68pin
 34pin
 1.27±0.1
 0.7±0.05 TYP.(68)
 35pin
 1pin
 1.8±0.1
 5.8
 8.1
 (5.08)
 41.91±0.1 (1.27±0.1X33)
 52.07±0.1
 0.635±0.1
 Ø2.6±0.1 TYP.(4)
 59±0.1
 4 CARD INSERTION

PDM: Rev:D STATUS: **Released** Printed: Nov 03, 2010

Technical drawing of a vertical section of a building joint, showing dimensions and components. The drawing includes a "JOINT DIRECTION" arrow pointing upwards. Key dimensions include 5.8 ± 0.2 , 2.8, 1.905, 0.7, 2.5 TYP(2), 7, 4, 3, and $H^* \pm 0.2$. Callouts (A) and (B) point to specific components. The drawing shows a vertical assembly with various layers and fasteners.

NOTE

1. EJECT FORCE 3.5Kg MAX.

2. ASSY PROCESS

2.1 TO MOUNT PART (A) ON PWB WITH 2 SCREWS (S1,S2) AND SOLDER.

2.2 TO JOINT PART (A) TO PART (A), THEN FIX PART (B) WITH 2 SCREWS (S3,S4).

3. PUSH ROD TRAVEL 8.0mm REF.

④ MATERIAL

4.1 PART (A), (HEADER ASSY)
HOUSING : LIQUID CRYSTAL POLYMER (LCP) UL94V-0
PIN : COPPER ALLOY
LOCATOR : 66NYLON UL94V-0 BLACK

4.2 PART (B), (EJECT MECHANISM ASSY)
GUIDE : POLYPHENYLENE SULFIDE (PPS) UL94V-0 BLACK
PUSH ROD : POLYPHTHARAMID SULFIDE (PPS) UL94V-0 BLACK
PLATES : STAINLESS STEEL

⑤ FINISH (PIN)

UNDER PLATING : 0.5 μ m MIN. Ni
CONTACT AREA : 0.1 μ m MIN. GOLD OVER 0.5 μ m MIN. Pd-Ni
SOLDER TAIL : 2.5 μ m MIN. Sn-Pb

6. DIM "X"

DIM "X"	5.0 \pm 0.1	3.5 \pm 0.1	4.25 \pm 0.1
PIN NO.	1, 17, 24 35, 51, 68	36, 67	OTHERS

7. SEE SHEET 1 REGARDING COMPONENTS.

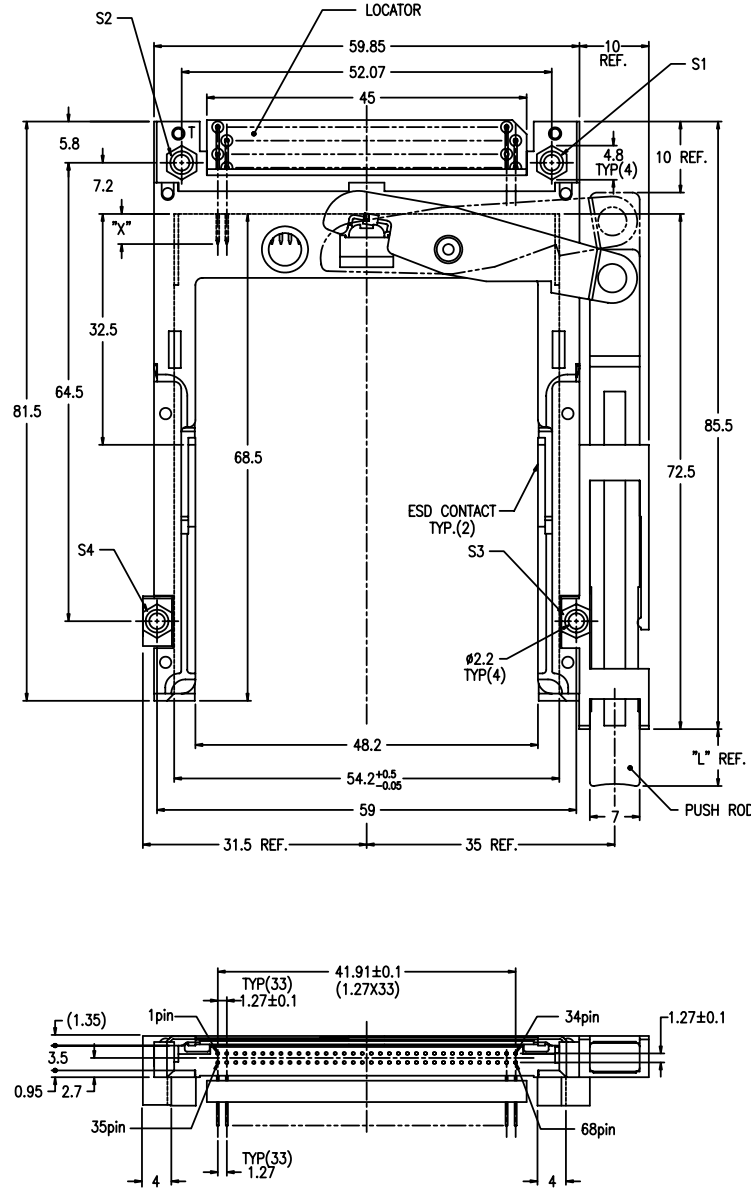
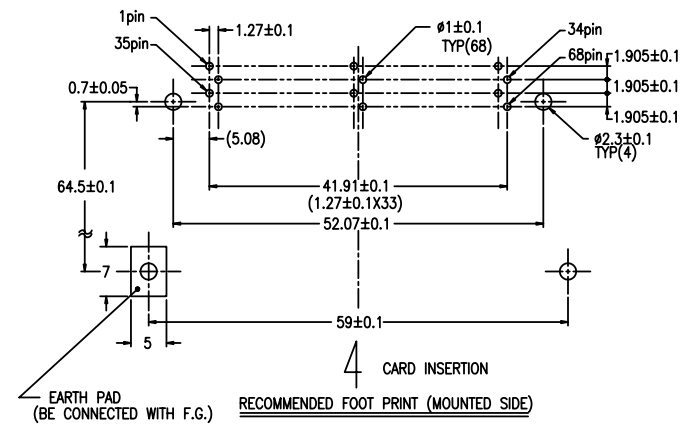
8. GENERAL TOLERANCE : \pm 0.3

9. IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.

10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-22-008

11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

7. SEE SHEET 1 REGARDING COMPONENTS.
8. GENERAL TOLERANCE : ± 0.3
9. IF LEAD FREE P/N, THE HOUSING WILL V
260° C PEAK TEMPERATURE FOR 10
APPLICATION WITH A 1.00MM MINIMUM
10. LEAD FREE PRODUCT MEETS EUROPEAN
COUNTRY REGULATIONS AS DISCRIBLE
11. IF LEAD FREE P/N, PACKAGE MEETS C

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